



SHINKAWA LTD.

News Release

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Shinkawa to Release High-Accuracy Twin-Head Die Bonder SPA-1000

Shinkawa Ltd. (President: Takashi Nagano, Headquarters: 51-1, Inadaira 2-chome, Musashi-Murayama-shi, Tokyo, Japan) has completed the development of the latest high-accuracy twin-head die bonder “SPA-1000” and has started accepting new orders.

Demand for high precision and high productivity bonding is increasing with the trend toward downsizing of packages. The SPA-1000 adopts Shinkawa’s distinctive three-dimensional non reaction servo system technology (3D-NRS), which enables the twin-head design. This contributes to high accuracy and high productivity as well as floor space savings in production sites. Furthermore, a total of eight high resolution cameras, including the die backside camera of each bonding head, enables precise inspection to improve product quality.



【Die Bonder SPA-1000】

【Features of SPA-1000】

- (1) Accuracy of $XY \pm 5\mu\text{m}$ (3σ) $\theta \pm 0.05^\circ$ (3σ)
*Machine accuracy excluding material-induced factors
- (2) High-productivity and space-saving footprint by adopting twin-head
- (3) High-speed thin die pick-up system with a speed of $400\text{ms/t:}20\mu\text{m}$ (option)
*Depending on material conditions
- (4) Friction-free bonding head with simultaneous positional and force control for thin die stacked devices
- (5) Cleanness control with HEPA-filter and stainless steel full cover
- (6) Enhanced inspection function with a total of 8 high resolution cameras
- (7) Capable of handling large substrates up to 120mm width x 300mm length

■ Other Product Line-ups

Wire Bonder, Flip Chip Bonder

■ Contact for Inquiry

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